

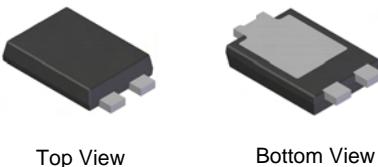
Features

- Lower Forward Voltage Drop than Ultrafast Rectifiers
- Very Low Leakage Current
- Soft Recovery Characteristics: Softness Factor (t_b/t_a) ≥ 1 (see figure 8)
- Highly Stable Oxide Passivated Junction
- High Forward Surge Current Capability
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

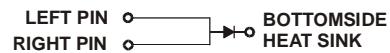
- Case: POWERDI5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 (e3)
- Polarity: See Diagram
- Weight: 0.095 grams (approximate)

POWERDI5



Top View

Bottom View



Note: Pins Left & Right must
be electrically connected
at the printed circuit board.

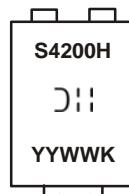
Ordering Information (Note 4)

| Part Number | Case | Packaging |
|-------------|----------|------------------|
| PDS4200H-13 | POWERDI5 | 5000/Tape & Reel |
| PDS4200H-7 | POWERDI5 | 1500/Tape & Reel |

Notes:

1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



S4200H = Product type marking code

DII = Manufacturers' code marking

YYWW = Date code marking

YY = Last two digits of year (ex: 06 for 2006)

WW = Week code (01 - 53)

K = Factory Designator

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitance load, derate current by 20%.

| Characteristic | Symbol | Value | Unit |
|---|---------------------|-------|------|
| Peak Repetitive Reverse Voltage | V_{RRM} | | |
| Working Peak Reverse Voltage | V_{RWM} | 200 | V |
| DC Blocking Voltage | V_R | | |
| RMS Reverse Voltage | $V_{R(\text{RMS})}$ | 141 | V |
| Average Rectified Output Current (See also figure 5) | I_O | 4 | A |
| Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave Superimposed on Rated Load | I_{FSM} | 100 | A |

Thermal Characteristics

| Characteristic | Symbol | Typ | Max | Unit |
|---|-----------------|-------------|-----|---------------------------|
| Thermal Resistance Junction to Soldering Point | $R_{\theta JS}$ | — | 3.0 | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance Junction to Ambient Air (Note 5) | $R_{\theta JA}$ | 80 | — | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance Junction to Ambient Air (Note 6) | $R_{\theta JA}$ | 65 | — | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance Junction to Ambient Air (Note 7) | $R_{\theta JA}$ | 45 | — | $^\circ\text{C}/\text{W}$ |
| Operating and Storage Temperature Range | T_J, T_{STG} | -65 to +175 | | $^\circ\text{C}$ |

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|------------------------------------|-------------|-----|-------|------|---------------|--|
| Reverse Breakdown Voltage (Note 8) | $V_{(BR)R}$ | 200 | — | — | V | $I_R = 5\mu\text{A}$ |
| Forward Voltage | V_F | — | 0.76 | 0.82 | V | $I_F = 3\text{A}, T_S = +25^\circ\text{C}$ |
| | | — | 0.59 | — | | $I_F = 3\text{A}, T_S = +150^\circ\text{C}$ |
| | | — | 0.785 | 0.84 | | $I_F = 4\text{A}, T_S = +25^\circ\text{C}$ |
| | | — | 0.61 | 0.64 | | $I_F = 4\text{A}, T_S = +150^\circ\text{C}$ |
| | | — | 0.84 | 0.89 | | $I_F = 8\text{A}, T_S = +25^\circ\text{C}$ |
| | | — | 0.68 | 0.75 | | $I_F = 8\text{A}, T_S = +150^\circ\text{C}$ |
| Reverse Leakage Current (Note 8) | I_R | — | 0.2 | 1 | μA | $T_S = +25^\circ\text{C}, V_R = 200\text{V}$ |
| | | — | 0.8 | 4 | mA | $T_S = +150^\circ\text{C}, V_R = 200\text{V}$ |
| Reverse Recovery Time | t_{rr} | — | — | 25 | ns | $I_F = 0.5\text{A}, I_R = 1.0\text{A}$ $I_{RR} = 0.25\text{A}$ (see Figure 8) |

Notes:

5. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.
6. Polyimide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.
7. Polyimide PCB, 2 oz. Copper. Cathode pad dimensions 9.4mm x 7.2mm. Anode pad dimensions 2.7mm x 1.6mm.
8. Short duration test pulse used to minimize self-heating effect.

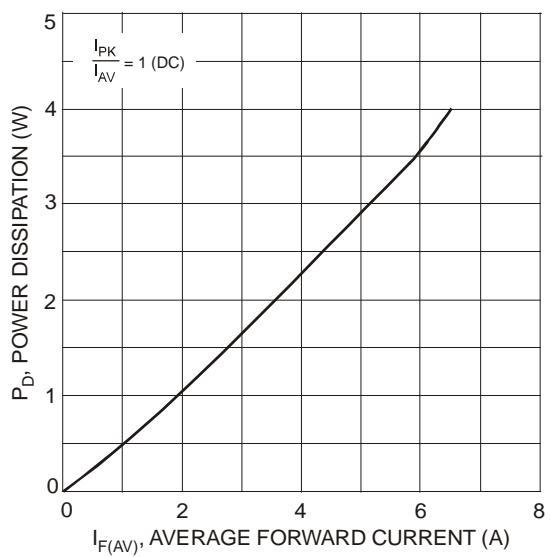


Fig. 1 Forward Power Dissipation

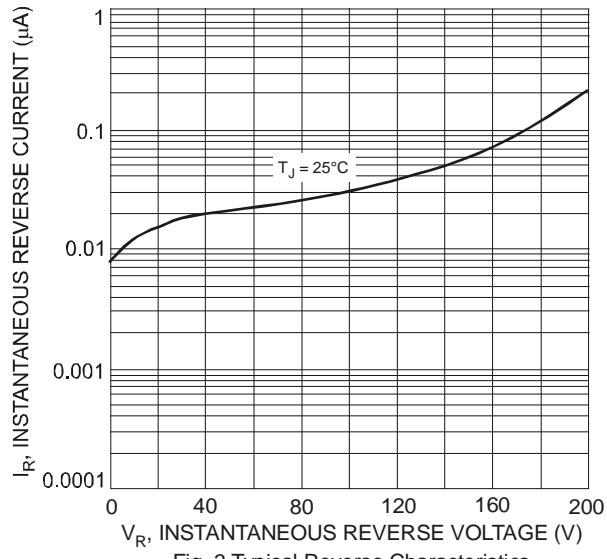


Fig. 3 Typical Reverse Characteristics

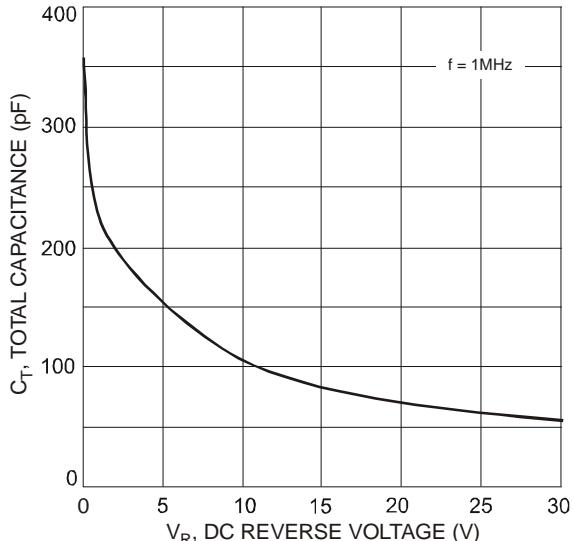


Fig. 5 Total Capacitance vs. Reverse Voltage

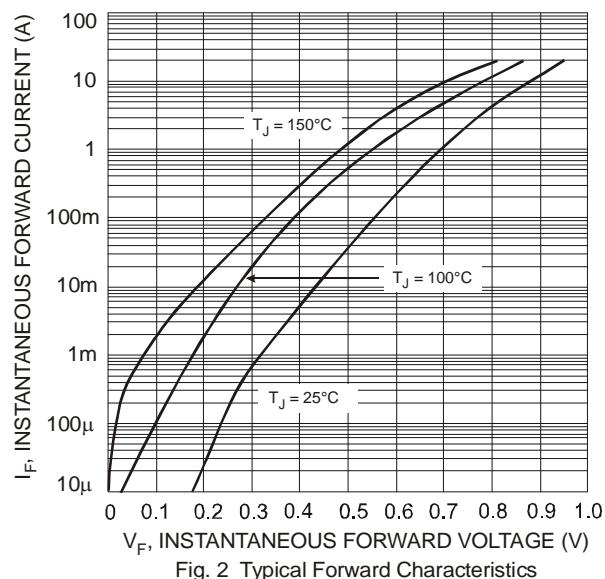


Fig. 2 Typical Forward Characteristics

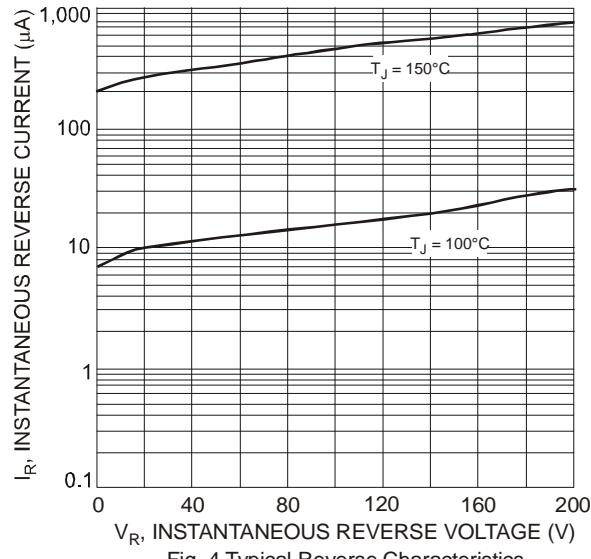


Fig. 4 Typical Reverse Characteristics

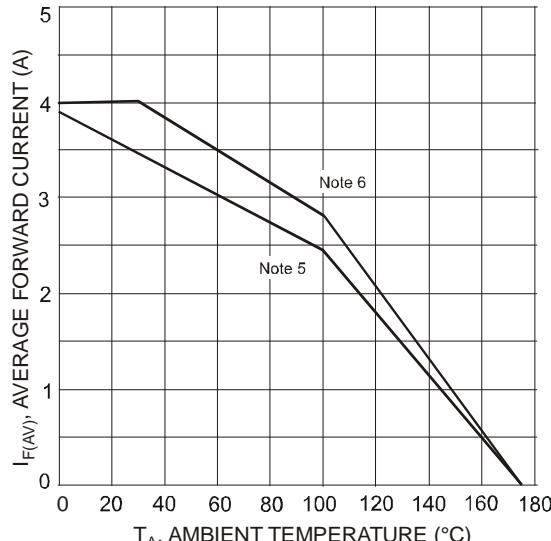


Fig. 6 Forward Current Derating Curve

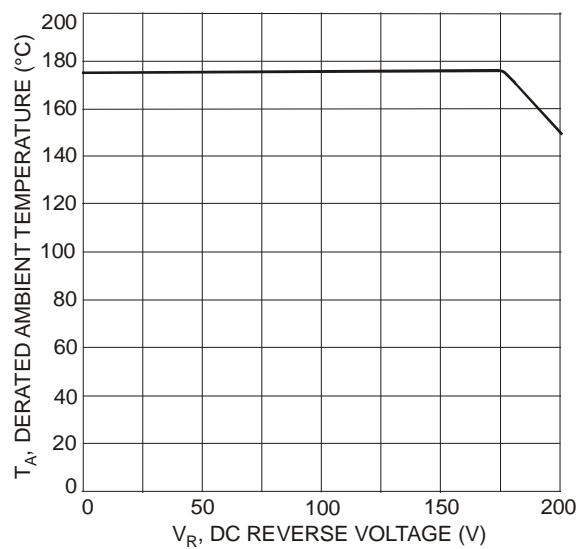
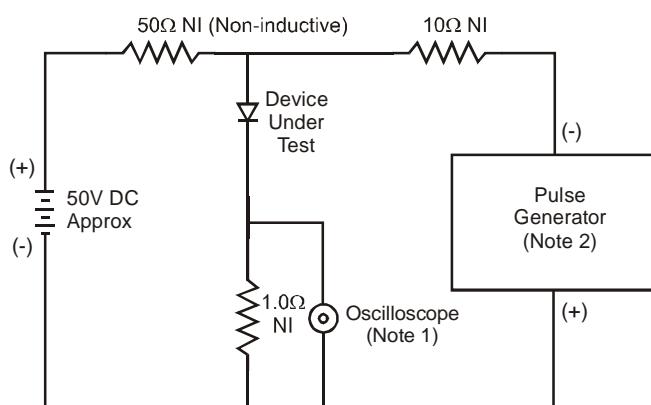


Fig. 7 Operating Temperature Derating



Notes:

1. Rise Time = 7.0ns max. Input Impedance = $1.0M\Omega$, 22pF.
2. Rise Time = 10ns max. Input Impedance = 50Ω .

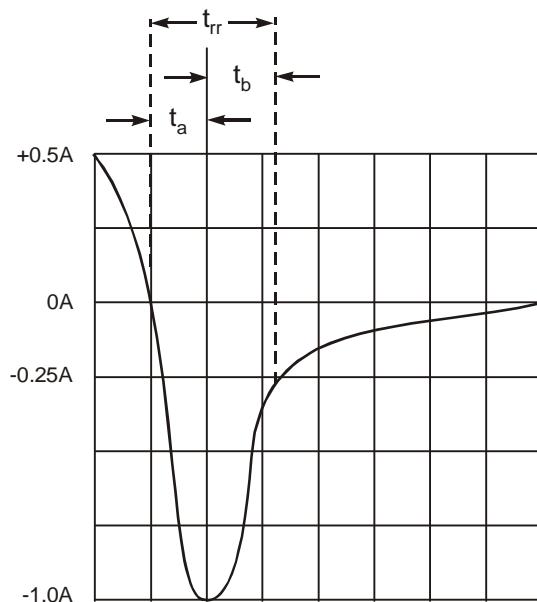
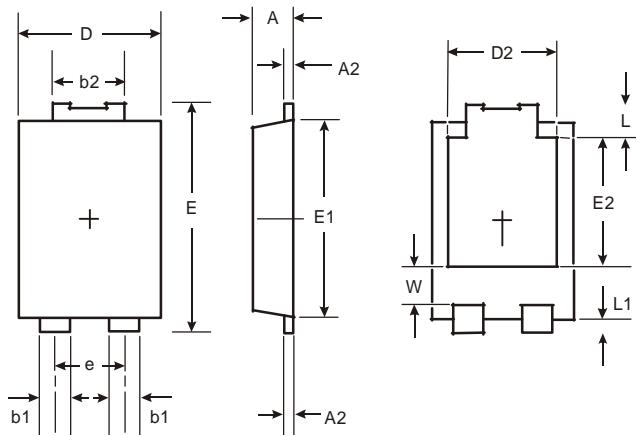


Fig. 8 Reverse Recovery Time Characteristic and Test Circuit

Package Outline Dimensions

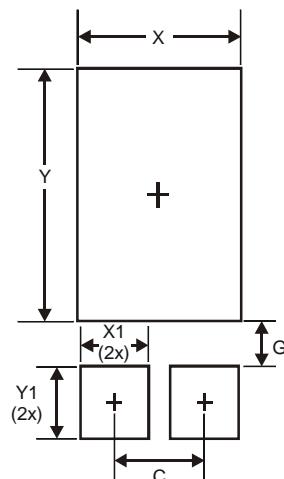
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



| POWERDI5 | | |
|----------------------|-----------|------|
| Dim | Min | Max |
| A | 1.05 | 1.15 |
| A2 | 0.33 | 0.43 |
| b1 | 0.80 | 0.99 |
| b2 | 1.70 | 1.88 |
| D | 3.90 | 4.05 |
| D2 | 3.054 Typ | |
| E | 6.40 | 6.60 |
| e | 1.84 Typ | |
| E1 | 5.30 | 5.45 |
| E2 | 3.549 Typ | |
| L | 0.75 | 0.95 |
| L1 | 0.50 | 0.65 |
| W | 1.10 | 1.41 |
| All Dimensions in mm | | |

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| C | 1.840 |
| G | 0.852 |
| X | 3.360 |
| X1 | 1.390 |
| Y | 4.860 |
| Y1 | 1.400 |

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